

# 2SA2029 / 2SA1774EB / 2SA1774 2SA1576UB / 2SA1576A / 2SA1037AK

General Purpose Transistor (-50V, -150mA)

Datasheet

Parameter	Value
V <sub>CEO</sub>	-50V
Ic	-150mA

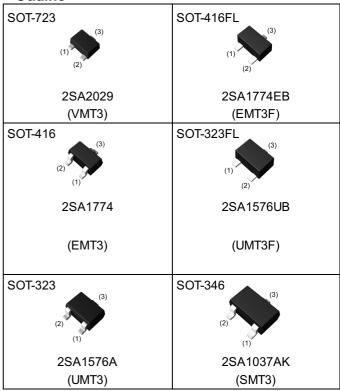
#### Features

- 1) General Purpose.
- 2) Complementary:2SC5658/2SC4617EB /2SC4617/2SC4081UB/2SC4081/2SC2412K
- 3) Lead Free/RoHS Compliant.

## Application

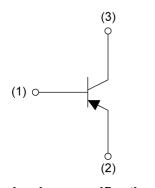
Switching circuit, LED driver circuit

## ●Outline



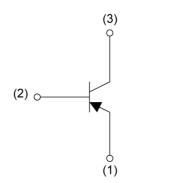
## ●Inner circuit

2SA2029/2SA1774EB/2SA1576UB



- (1) Base
- (2) Emitter
- (3) Collector

#### 2SA1774/2SA1576A/2SA1037AK



- (1) Emitter
- (2) Base
- (3) Collector

## Packaging specifications

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Part N	lo.	Package	Package size	Taping code	Reel size (mm)	Tape width (mm)	Basic ordering unit.(pcs)	hFE rank	Marking
2SA20	)29	SOT-723	1212	T2L	180	8	8000	QRS	F
2SA177	4EB	SOT-416FL	1616	TL	180	8	3000	QRS	F
2SA17	774	SOT-416	1616	TL	180	8	3000	QRS	F
2SA157	6UB	SOT-323FL	2021	TL	180	8	3000	QRS	F
2SA15	76A	SOT-323	2021	T106	180	8	3000	QRS	F
2SA103	37AK	SOT-346	2928	T146	180	8	3000	QRS	F

## ● Absolute maximum ratings (T<sub>a</sub> = 25°C)

Parameter			Values	Unit
Collector-base voltage	V <sub>CBO</sub>	-60	V	
Collector-emitter voltage		V <sub>CEO</sub>	-50	V
Emitter-base voltage		V <sub>EBO</sub>	-6	V
Callanton accuración		I <sub>C</sub>	-150	mA
Collector current		I <sub>CP</sub> *1	-200	mA
	2SA2029		150	
	2SA1774EB		150	
Davier dia sin etia e	2SA1774	D *2	150	\//
Power dissipation	2SA1576UB	P <sub>D</sub> *2	200	mW
	2SA1576A		200	
	2SA1037AK		200	
Junction temperature	<u>.</u>	T <sub>j</sub>	150	°C
Range of storage tempera	T <sub>stg</sub>	-55 to +150	°C	

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Darameter	Cumbal	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Collector-base breakdown voltage	BV <sub>CBO</sub>	I <sub>C</sub> = -50μA	-60	1	-	V
Collector-emitter breakdown voltage	BV <sub>CEO</sub>	I <sub>C</sub> = -1mA	-50	1	-	<b>V</b>
Emitter-base breakdown voltage	BV <sub>EBO</sub>	I <sub>E</sub> = -50μA	49	1	1	V
Collector cut-off current	I <sub>CBO</sub>	V <sub>CB</sub> = -60V	ı	1	-100	nA
Emitter cut-off current	I <sub>EBO</sub>	V <sub>EB</sub> = -6V	ı	1	-100	nA
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = -50 \text{mA}, I_B = -5 \text{mA}$	ı	1	-500	mV
DC current gain	h <sub>FE</sub>	$V_{CE} = -6V, I_{C} = -1mA$	120	1	560	-
Transition frequency	f <sub>T</sub>	$V_{CE} = -12V, I_{E} = 2mA,$ f = 100MHz	-	140	-	MHz
Output capacitance	$C_{ob}$	$V_{CB} = -12V, I_{E} = 0A,$ f = 1MHz	ı	4.0	5.0	pF

### hFE values are calssified as follows:

rank	Q	R	S	-	-
h <sub>FE</sub>	120-270	180-390	270-560	-	-

<sup>\*1</sup> Pw=1ms Single Pulse



<sup>\*2</sup> Each terminal mounted on a reference footprint

## ● Electrical characteristic curves(T<sub>a</sub> = 25°C)

Fig.1 Ground Emitter Propagation Characteristics

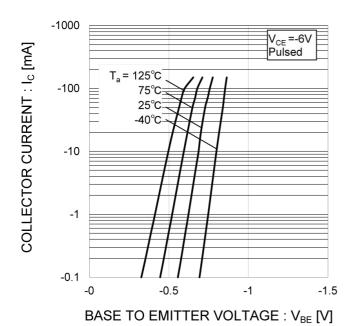
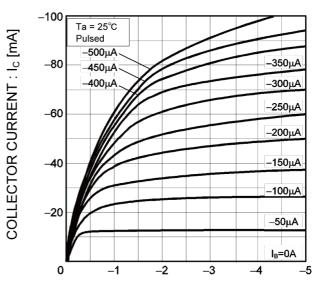


Fig.2 Typical Output Characteristics



COLLECTOR TO EMITTER VOLTAGE: V<sub>CE</sub> [V]

Fig.3 DC Current Gain vs. Collector Current (I)

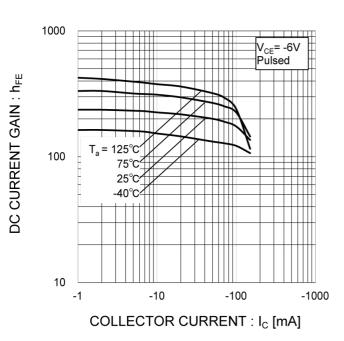
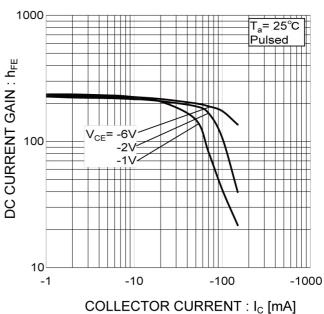


Fig.4 DC Current Gain vs. Collector Current (II)



## ● Electrical characteristic curves(T<sub>a</sub> = 25°C)

Fig.5 Collector-Emitter Saturation Voltage vs. Collector Current (I)

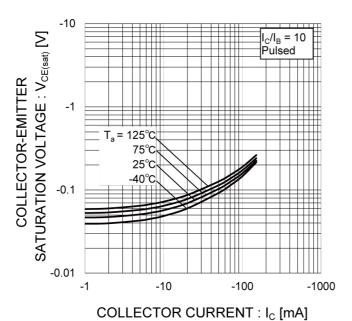
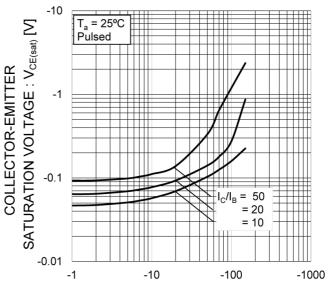


Fig.6 Collector-Emitter Saturation Voltage vs. Collector Current (II)



COLLECTOR CURRENT : I<sub>C</sub> [mA]

Fig.7 Base-Emitter Saturation Voltage vs. Collector Current

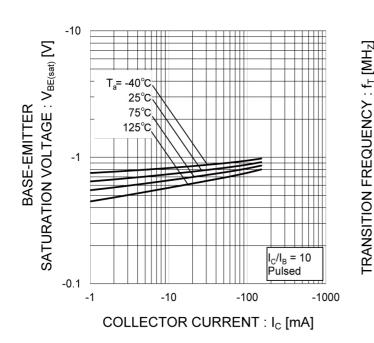
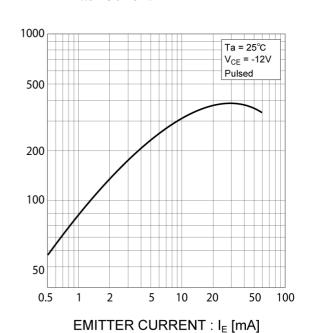


Fig.8 Gain Bandwidth Product vs. Emitter Current



## ● Electrical characteristic curves(T<sub>a</sub> = 25°C)

Fig.9 Emitter Input Capacitance vs.
Emitter-Base Voltage
Collector Output Capacitance vs.
Collector-Base Voltage

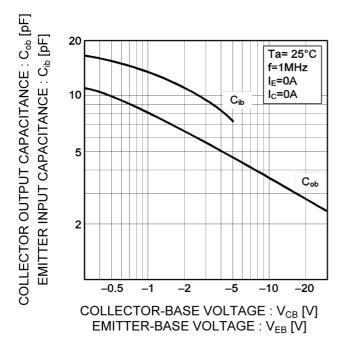


Fig.10 Safe Operating Area

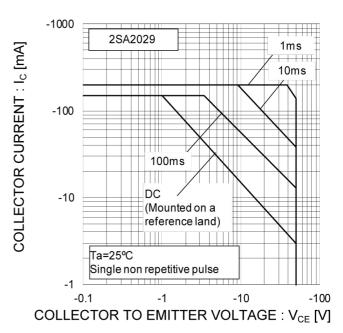


Fig.11 Safe Operating Area

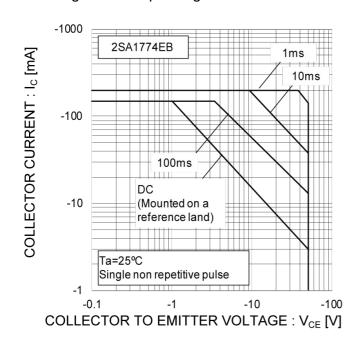
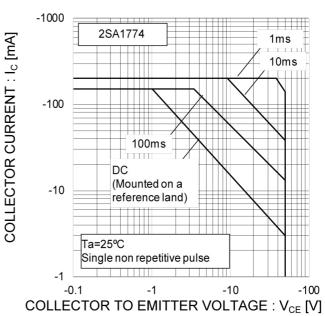


Fig.12 Safe Operating Area



## ● Electrical characteristic curves(Ta=25°C)

Fig.13 Safe Operating Area

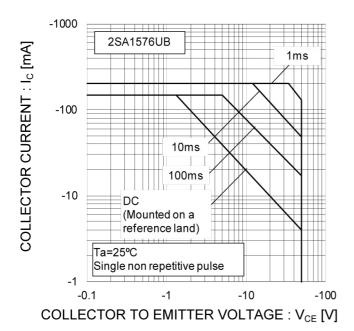


Fig.14 Safe Operating Area

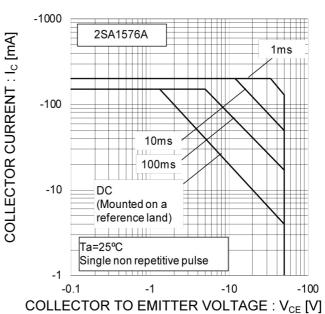
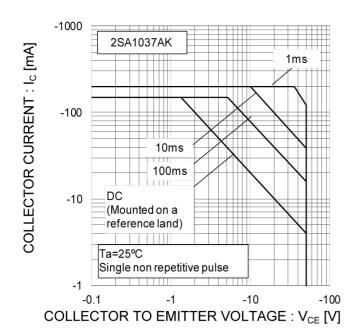
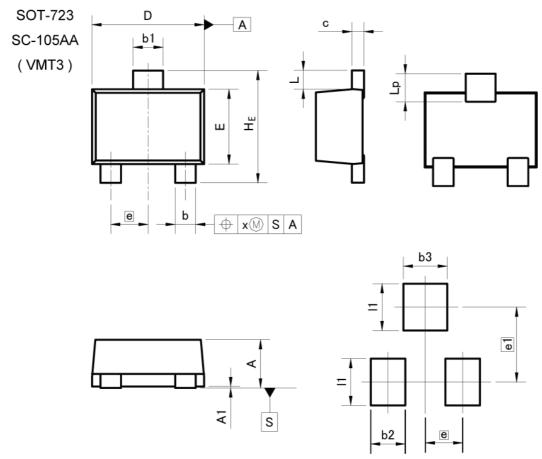


Fig.15 Safe Operating Area







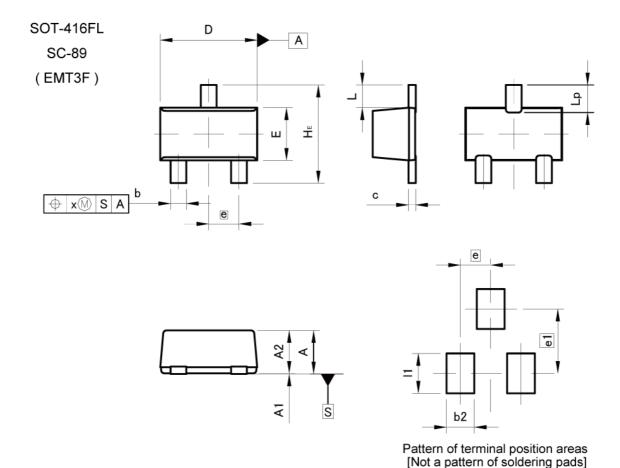
Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	MILIMETERS		HES
DIM	MIN	MAX	MIN	MAX
Α	0.45	0.55	0.018	0.022
A1	0.00	0.10	0.000	0.004
b	0.17	0.27	0.007	0.011
b1	0.27	0.37	0.011	0.015
С	0.08	0.18	0.003	0.007
D	1.10	1.30	0.043	0.051
E	0.70	0.90	0.028	0.035
е	0.40 0.02		02	
HE	1.10	1.30	0.043	0.051
L	0.10	0.30	0.004	0.012
Lp	0.20	0.40	0.008	0.016
х	-	0.10	_	0.004

DIM	MILIM	ETERS	INCHES		
	MIN	MAX	MIN	MAX	
b2	-	0.37	_	0.015	
b3	_	0.47	7-	0.019	
e1	0.80		e1 0.80 0.031		31
11	=	0.50		0.020	

Dimension in mm/inches



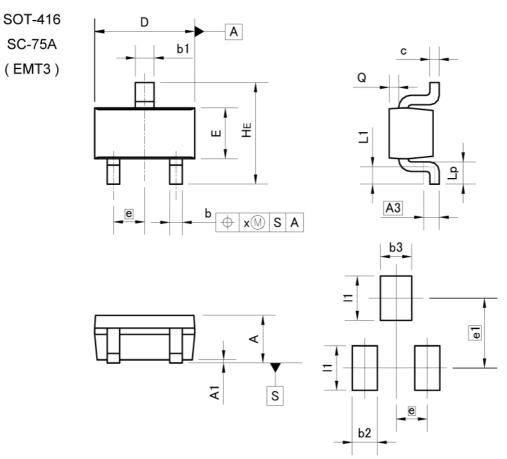


**INCHES MILIMETERS** DIM MIN MAX MIN MAX 0.85 0.033 0.65 0.026 Α Α1 0.00 0.10 0.000 0.004 0.60 0.80 0.024 0.031 A2 b 0.21 0.36 0.008 0.014 0.007 0.08 0.18 0.003 С D 1.50 1.70 0.059 0.067 0.030 Е 0.76 0.96 0.038 0.50 0.020 е HE 1.50 1.70 0.059 0.067 0.37 0.015 L 0.35 0.55 0.014 0.022 Lр 0.10 0.004 X

DIM	MILIMETERS		INCHES		
	MIN	MAX	MIN	MAX	
b2	_	0.46	_	0.018	
e1	_	1.05	-	0.041	
- 11	-	0.65	-	0.026	

Dimension in mm/inches





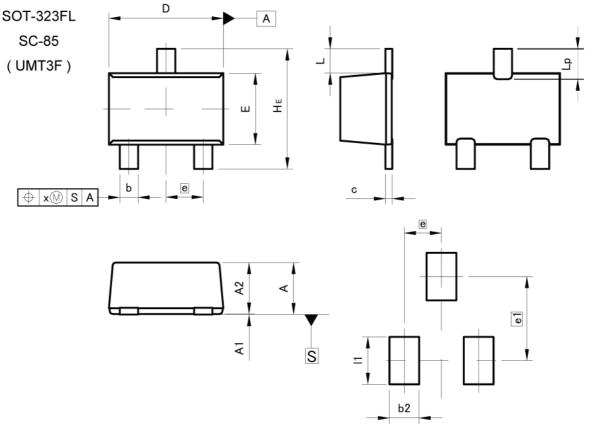
Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	METERS INC		HES
DIM	MIN	MAX	MIN	MAX
Α	0.60	0.80	0.024	0.031
A1	0.00	0.10	0.000	0.004
A3	0.	25	0.0	10
b	0.15	0.30	0.006	0.012
b1	0.25	0.40	0.010	0.016
С	0.10	0.20	0.004	0.008
D	1.50	1.70	0.059	0.067
E	0.70	0.90	0.028	0.035
е	0.	50	0.020	
HE	1.40	1.80	0.055	0.071
L1	0.10	-	0.004	-
Lp	0.15		0.006	×-
Q	0.05	0.25	0.002	0.010
х	-	0.10	,-	0.004

DIM	MILIM	MILIMETERS		INCHES		
	MIN	MAX	MIN	MAX		
b2	-	0.40	-	0.016		
b3	-	0.50	-	0.020		
e1	1.	1.10		1.10 0.043		143
- 11	1,=	0.70	-	0.028		

Dimension in mm/inches





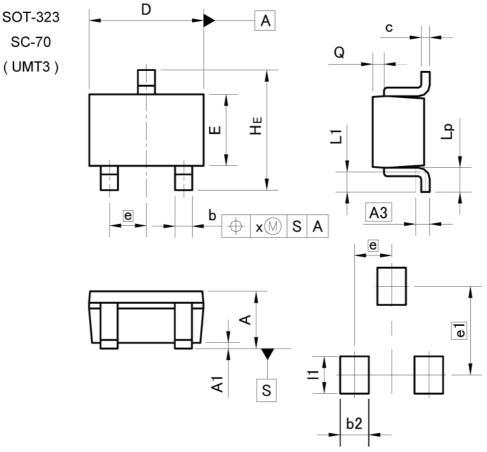
Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIMETERS		ERS INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	0.85	1.05	0.033	0.041	
A1	0.00	0.10	0.000	0.004	
A2	0.80	1.00	0.031	0.039	
b	0.27	0.42	0.011	0.017	
С	0.08	0.18	0.003	0.007	
D	1.90	2.10	0.075	0.083	
E	1.15	1.35	0.045	0.053	
е	0.0	65	0.026		
HE	2.00	2.20	0.079	0.087	
L	0.43		L 0.43 0.017		17
Lp	0.43	0.63	0.017	0.025	
х	_	0.10	-	0.004	

	DIM	MILIM	MILIMETERS		HES
		MIN	MAX	MIN	MAX
	b2	-	0.52	ı	0.020
	e1	1.47		0.0	58
	l1	-	0.83	=	0.033

Dimension in mm/inches





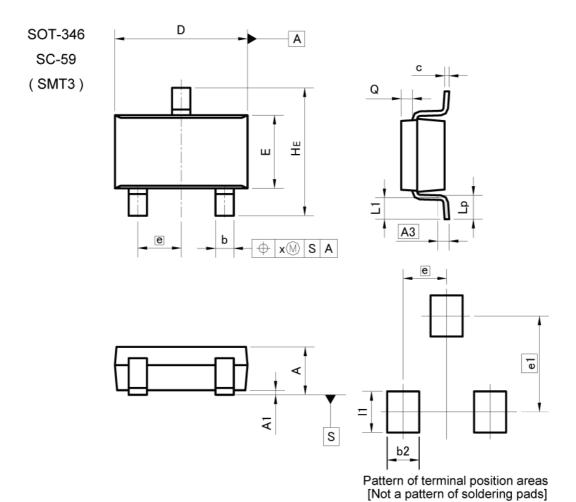
Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
Α	0.80	1.00	0.031	0.039
A1	0.00	0.10	0	0.004
A3	0.25		0.01	
b	0.25	0.40	0.01	0.016
С	0.10	0.20	0.004	0.008
D	1.90	2.10	0.075	0.083
E	1.15	1.35	0.045	0.053
е	0.65		0.03	
HE	2.00	2.20	0.079	0.087
L1	0.20	0.50	0.008	0.02
Lp	0.25	0.55	0.01	0.022
Q	0.10	0.30	0.004	0.012
х	_	0.10	_	0.004

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
e1	1.55		0.06	
b2	-	0.50	1	0.02
11	_	0.65	_	0.026

Dimension in mm/inches





DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
Α	1.00	1.30	0.039	0.051
A1	0.00	0.10	0.000	0.004
A3	0.25		0.010	
b	0.35	0.50	0.014	0.020
С	0.09	0.25	0.004	0.010
D	2.80	3.00	0.110	0.118
E	1.50	1.80	0.059	0.071
е	0.95		0.037	
HE	2.60	3.00	0.102	0.118
L1	0.30	0.60	0.012	0.024
Lp	0.40	0.70	0.016	0.028
Q	0.20	0.30	0.008	0.012
х	- 2	0.10	-	0.004
У	-,,,	0.10	-	0.004

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b2	-	0.60	-	0.024
e1	2.10		0.083	
- 11	-3	0.90	-	0.035

Dimension in mm/inches



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  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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